



PK460 (v1.0) May 20, 2011

# 100% Material Declaration Data Sheet CSG484 for Spartan-6 FPGAs

**Average Weight: 1.2740 g**

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
<b>Silicon Die</b>					<b>0.033116</b>	<b>2.599%</b>
	Silicon	7440-21-3	100.00		0.033116	
<b>Die Attach Material</b>					<b>0.010225</b>	<b>0.803%</b>
	Silver	7440-22-4	77.50		0.007924	
	Bismaleimide monomer	Trade Secret	15.00		0.001534	
	Acrylate monomer	Trade Secret	7.50		0.000767	
<b>Mold Compound</b>					<b>0.472284</b>	<b>37.071%</b>
	Solid Epoxy Resin	Trade Secret	5.00		0.023614	
	Phenol Resin	Trade Secret	5.00		0.023614	
	Fused Silica	60676-86-0	87.45		0.413012	
	Metal Hydroxide	Trade Secret	2.00		0.009446	
	Carbon Black	1333-86-4	0.55		0.002598	
<b>Gold Wire</b>					<b>0.016904</b>	<b>1.327%</b>
	Gold	7440-57-5	99.05		0.016743	
	Palladium	7440-05-3	0.95		0.000161	
	Calcium	7440-70-2	0.00		0.000000	
<b>Solder Balls</b>					<b>0.171033</b>	<b>13.425%</b>
	Tin	7440-31-5	96.50		0.165047	
	Silver	7440-22-4	3.00		0.005131	
	Copper	7440-50-8	0.50		0.000855	
<b>Substrate</b>					<b>0.570438</b>	<b>44.775%</b>
	Copper	7440-50-8	45.61		0.260162	
	Nickel	7440-02-0	0.96		0.005488	
	Gold	7440-57-5	0.16		0.000936	
	BT (core)	21645-51-2/ 7440-50-8/ Epoxy resin	48.94		0.279192	
	Solder mask	14807-96-6/ 7727-43-7/ 7631- 86-9/ 34590-94-8/ 85954-11-6	4.32		0.024660	

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## Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
5/20/11	1.0	Initial Xilinx release.

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